

**U.S. DEPARTMENT OF COMMERCE  
PATENT AND TRADEMARK OFFICE**

ATTY. DOCKET NO.  
**ALLEG-039PUS**

APPLICATION NO.  
**10/649,450**

**INFORMATION DISCLOSURE CITATION**

*(Use several sheets if necessary)*

APPLICANT  
**Michael Doogue, et al.**

FILING DATE  
**August 26, 2003**

GROUP  
**2831**

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**U.S. PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB- CLASS	FILING DATE IF APPROPRIATE*

**FOREIGN PATENT DOCUMENTS**

EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB-CLASS	TRANSLATION	
							YES	NO

**OTHER DOCUMENTS (including Author, Title, Date, Pertinent Pages, Etc.)**

/HN/		EP Office Action dated June 17, 2009; for EP Pat. App. No. 048163162.4 (Atty. Dckt. No. ALLEG-039PEP)
/HN/		Lee et al.; "Fine Pitch Au-SnAgCu Joint-in-via Flip-Chip Packaging;" IEEE 9 <sup>th</sup> Electronics Packaging Technology Conference, December 10-12, 2007; Pages 1-7
Examiner		<div><div>/Hung Ngo/</div><div>Date Considered: 12/07/2009</div></div> <div>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and considered. Include copy of this form with next communication to applicant.</div>